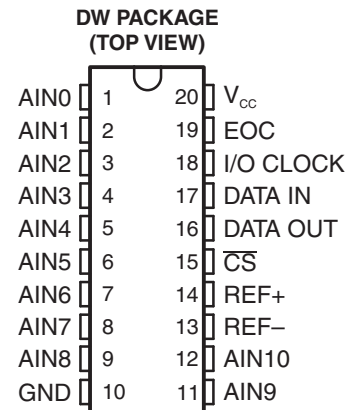# 12-BIT 200-KSPS 11-CHANNEL LOW-POWER SERIAL ADC

FEATURES

- **Qualified for Automotive Applications**
- **12-Bit-Resolution Analog-to-Digital Converter (ADC)**
- **Up to 200-KSPS (150-KSPS for 3 V) Throughput Over Operating Temperature Range With 12-Bit Output Mode**
- **11 Analog Input Channels**
- **Three Built-In Self-Test Modes**
- **Inherent Sample and Hold Function**
- **Linearity Error of +1 LSB (Max)**
- **On-Chip Conversion Clock**
- **Unipolar or Bipolar Output Operation**
- **Programmable Most Significant Bit (MSB) or Least Significant Bit (LSB) First**
- **Programmable Power Down**
- **Programmable Output Data Length**
- **SPI Compatible Serial Interface With I/O Clock Frequencies up to 15 MHz (CPOL=0, CPHA=0)**

APPLICATIONS

- **Process Control**
- **Portable Data Logging**
- **Battery-Powered Instruments**
- **Automotive**

DW PACKAGE
(TOP VIEW)

AIN0	1	20	V_{CC}
AIN1	2	19	EOC
AIN2	3	18	I/O CLOCK
AIN3	4	17	DATA IN
AIN4	5	16	DATA OUT
AIN5	6	15	$\overline{CS}$
AIN6	7	14	REF+
AIN7	8	13	REF−
AIN8	9	12	AIN10
GND	10	11	AIN9

DESCRIPTION\ORDERING INFORMATION

The TLV2553 is a 12-bit switched-capacitor successive-approximation analog-to-digital converter (ADC). The ADC has three control inputs [chip select ($\overline{CS}$), the input-output clock, and the address/control input (DATAIN)] designed for communication with the serial port of a host processor or peripheral through a serial 3-state output.

In addition to the high-speed converter and versatile control capability, the device has an on-chip 14-channel multiplexer that can select any one of 11 inputs or any one of three internal self-test voltages using configuration register 1. The sample-and-hold function is automatic. At the end of conversion, when programmed as EOC, the pin 19 output goes high to indicate that conversion is complete. The converter incorporated in the device features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating temperature range.

The TLV2553I is characterized for operation from T_A = −40°C to 85°C.

ORDERING INFORMATION[1]

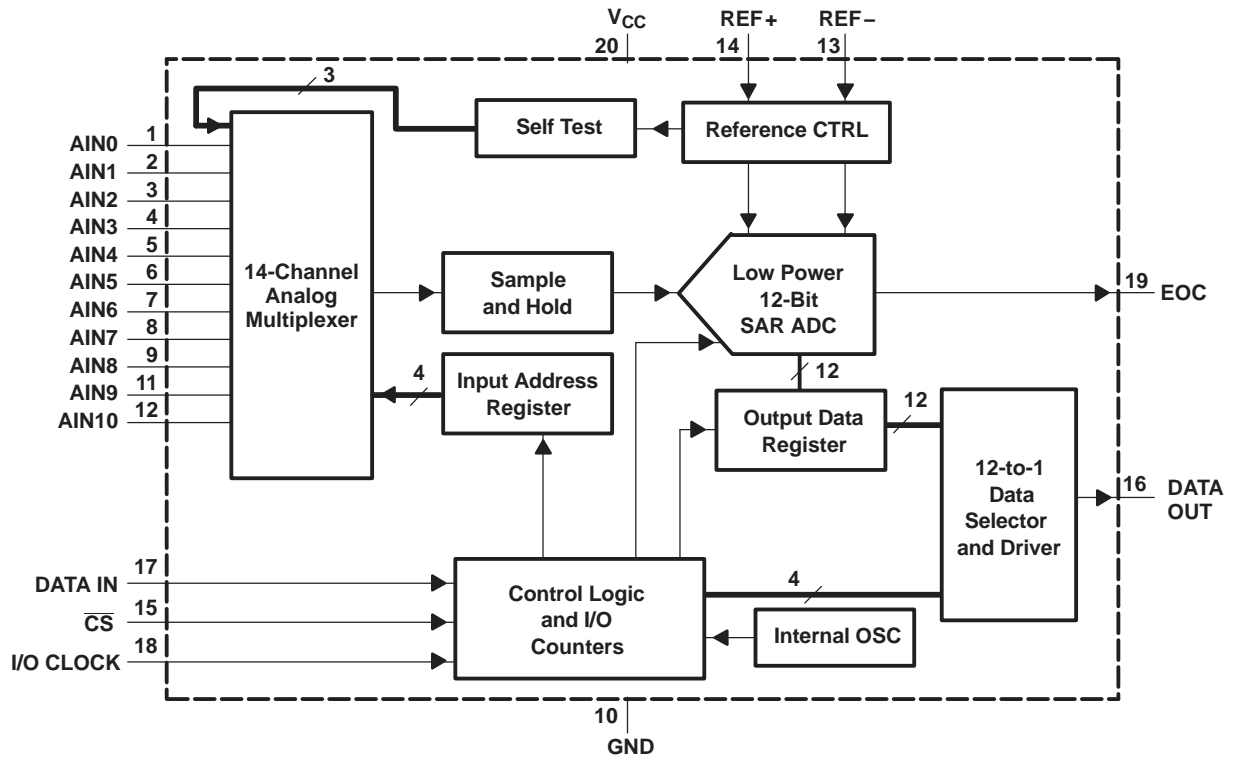| T_A	PACKAGE[2]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOP – DW	Reel of 2000	TLV2553IDWRQ1	TLV2553IQ1

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTIONAL BLOCK DIAGRAM

TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
AIN0–AIN10	1–9, 11, 12	I	Analog input. These 11 analog-signal inputs are internally multiplexed.
$\overline{CS}$	15	I	Chip select. A high-to-low transition on $\overline{CS}$ resets the internal counters and controls and enables DATA OUT, DATA IN, and I/O CLOCK. A low-to-high transition disables DATA IN and I/O CLOCK within a setup time.
DATA IN	17	I	Serial data input. The 4-bit serial data can be used as address selects the desired analog input channel or test voltage to be converted next, or a command to activate other other features. The input data is presented with the MSB (D7) first and is shifted in on the first four rising edges of the I/O CLOCK. After the four address/command bits are read into the command register CMR, I/O CLOCK clocks the remaining four bits of configuration in.
DATA OUT	16	O	3-state serial output for the A/D conversion result. DATA OUT is in the high-impedance state when $\overline{CS}$ is high and active when $\overline{CS}$ is low. With a valid $\overline{CS}$, DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB/LSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next MSB/LSB, and the remaining bits are shifted out in order.
EOC	19	O	End-of-convertions status. Used to indicate the end of conversion (EOC) to the host processor. EOC goes from a high to a low logic level after the falling edge of the last I/O CLOCK and remains low until the conversion is complete and the data is ready for transfer.
GND	10		Ground. GND is the ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	18	I	Input /output clock. I/O CLOCK receives the serial input and performs the following four functions: 1. It clocks the eight input data bits into the input data register on the first eight rising edges of I/O CLOCK with the multiplexer address available after the fourth rising edge. 2. On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplexer input begins charging the capacitor array and continues to do so until the last falling edge of I/O CLOCK. 3. The remaining 11 bits of the previous conversion data are shifted out on DATA OUT. Data changes on the falling edge of I/O CLOCK. 4. Control of the conversion is transferred to the internal state controller on the falling edge of the last I/O CLOCK.
REF+	14	I/O	Positive reference voltage The upper reference voltage value (nominally V_{CC}) is applied to REF+. The maximum analog input voltage range is determined by the difference between the voltage applied to terminals REF+ and REF–.
REF–	13	I/O	Negative reference voltage. The lower reference voltage value (nominally ground) is applied to REF–. This pin is connected to analog ground (GND of the ADC) when internal reference is used.
V_{CC}	20		Positive supply voltage

ABSOLUTE MAXIMUM RATINGS[1]

over operating free-air temperature range (unless otherwise noted)

		VALUE
V_{CC}	Supply voltage range[2]	−0.5 V to 6.5 V
V_I	Input voltage range (any input)	−0.3 V to V_{CC} + 0.3
V_O	Output voltage range	−0.3 V to V_{CC} + 0.3
V_{ref+}	Positive reference voltage range	−0.3 V to V_{CC} + 0.3
V_{ref-}	Negative reference voltage range	−0.3 V to V_{CC} + 0.3
I_I	Peak input current (any input)	±20 mA
	Peak total input current (all inputs)	±30 mA
T_J	Operating virtual junction temperature range	−40°C to 150°C
T_A	Operating free-air temperature range	−40°C to 85°C
T_{stg}	Storage temperature range	−65°C to 150°C
	Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to the GND terminal with REF− and GND wired together (unless otherwise noted).

RECOMMENDED OPERATING CONDITIONS

				MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage			2.7		5.5	V
	I/O CLOCK frequency	V_{CC} = 4.5 V to 5.5 V	16-bit I/O	0.01		15	MHz
			12-bit I/O	0.01		15	
			18-bit I/O	0.01		15	
		V_{CC} = 2.7 to 3.6 V		0.01		10	
	Tolerable clock jitter, I/O CLOCK	V_{CC} = 4.5 V to 5.5 V				0.38	ns
	Aperature jitter	V_{CC} = 4.5 V to 5.5 V			100		ps
	Analog input voltage[1]	V_{CC} = 4.5 V to 5.5 V		0		REF+ − REF−	V
		V_{CC} = 3 V to 3.6 V		0			
		V_{CC} = 2.7 V to 3 V		0			
V_{IH}	High-level control input voltage	V_{CC} = 4.5 V to 5.5 V		2			V
		V_{CC} = 2.7 V to 3.6 V		2.1			
V_{IL}	Low-level control input voltage	V_{CC} = 4.5 V to 5.5 V				0.8	V
		V_{CC} = 2.7 V to 3.6 V				0.6	
T_A	Operating free-air temperature			−40		85	°C

(1) Analog input voltages greater than the voltage applied to REF+ convert as all ones (111111111111), while input voltages less than the voltage applied to REF− convert as all zeros (000000000000).

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, when V_{CC} = 5 V: V_{REF+} = 5 V, I/O CLOCK frequency = 15 MHz, when V_{CC} = 2.7 V: V_{REF+} = 2.5 V, I/O CLOCK frequency = 10 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP[1]	MAX	UNIT
V_{OH}	High-level output voltage	V_{CC} = 4.5 V, I_{OH} = −1.6 mA V_{CC} = 2.7 V, I_{OH} = −0.2 mA		30 pF	2.4			V
		V_{CC} = 4.5 V, I_{OH} = −20 μA V_{CC} = 2.7 V, I_{OH} = −20 μA			V_{CC} − 0.1			
V_{OL}	Low-level output voltage	V_{CC} = 4.5 V, I_{OL} = −1.6 mA V_{CC} = 2.7 V, I_{OL} = −0.8 mA		30 pF			0.4	V
		V_{CC} = 4.5 V, I_{OL} = −20 μA V_{CC} = 2.7 V, I_{OL} = −20 μA					0.1	
I_{OZ}	High-impedance off-state output current	V_O = V_{CC}, $\overline{CS}$ = V_{CC}				1	2.5	μA
		V_O = 0 V, $\overline{CS}$ = V_{CC}				−1	−2.5	
I_{CC}	Operating supply current	$\overline{CS}$ = 0 V, External reference	V_{CC} = 5 V				1.2	mA
			V_{CC} = 2.7 V				0.9	
$I_{CC(PD)}$	Power-down current	For all digital inputs, 0 ≤ V_I ≤ 0.5 V or V_I ≥ V_{CC} − 0.5 V, I/O CLOCK = 0 V	Software power down			0.1	1	μA
			Auto power down			0.1	10	
I_{IH}	High-level input current	V_I = V_{CC}				0.005	2.5	μA
I_{IL}	Low-level input current	V_I = 0 V				−0.005	−2.5	μA
I_{lkg}	Selected channel leakage current	Selected channel at V_{CC}, Unselected channel at 0 V					1	μA
		Selected channel at 0 V, Unselected channel at V_{CC}					−1	
f_{OSC}	Internal oscillator frequency	V_{CC} = 4.5 V to 5.5 V			3.27			MHz
		V_{CC} = 2.7 V to 3.6 V			2.56			
$t_{convert}$	Conversion time (13.5 × (1/f_{OSC}) + 25 ns)	V_{CC} = 4.5 V to 5.5 V					4.15	μs
		V_{CC} = 2.7 V to 3.6 V					5.54	
	Internal oscillator frequency voltage					3.6	4.1	V
Z_i	Input impedance[2]	Analog inputs	V_{CC} = 4.5 V				500	Ω
			V_{CC} = 2.7 V				600	
C_i	Input capacitance	Analog inputs				45	55	pF
		Control inputs				5	15	

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C.
(2) The switch resistance is very nonlinear and varies with input voltage and supply voltage. This is the worst case.

EXTERNAL REFERENCE SPECIFICATIONS[1]

PARAMETER		TEST CONDITIONS		MIN	TYP[2]	MAX	UNIT
V_{REF-}	Reference input voltage, REF–	V_{CC} = 4.5 V to 5.5 V		–0.1	0	0.1	V
		V_{CC} = 2.7 V to 3.6 V		–0.1	0	0.1	
V_{REF+}	Reference input voltage, REF+	V_{CC} = 4.5 V to 5.5 V		2		V_{CC}	V
		V_{CC} = 2.7 V to 3.6 V		2		V_{CC}	
	External reference input voltage difference (REF+ – REF–)	V_{CC} = 4.5 V to 5.5 V		1.9		V_{CC}	V
		V_{CC} = 2.7 V to 3.6 V		1.9		V_{CC}	
I_{REF}	External reference supply current	$\overline{CS}$ = 0 V	V_{CC} = 4.5 V to 5.5 V			0.94	mA
			V_{CC} = 2.7 V to 3.6 V			0.62	
Z_{REF}	Reference input impedance	V_{CC} = 5 V	Static	1			MΩ
			During sampling/conversion	6		9	kΩ
		V_{CC} = 2.7 V	Static	1			MΩ
			During sampling/conversion	6		9	kΩ

(1) Add a 0.1-µF capacitor between REF+ and REF– pins when external reference is used.
(2) All typical values are at V_{CC} = 5 V, T_A = 25°C.

OPERATING CHARACTERISTICS

over recommended operating free-air temperature range, when V_{CC} = 5 V: V_{REF+} = 5 V, I/O CLOCK frequency = 15 MHz, when V_{CC} = 2.7 V: V_{REF+} = 2.5 V, I/O CLOCK frequency = 10 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP[1]	MAX	UNIT
INL	Integral linearity error[2]		–1		1	LSB
DNL	Differential linearity error		–1		1	LSB
E_O	Offset error[3]	See [4]	–2		2	mV
E_G	Gain error[3]	See [4]	–3		3	mV
E_T	Total unadjusted error[5]			±1.5		LSB
	Self-test output code[6] (see Table 2)	Address data input = 1011		2048		
		Address data input = 1100		0		
		Address data input = 1101		4095		

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C.
(2) Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
(3) Gain error is the difference between the actual midstep value and the nominal midstep value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero. Offset error is the difference between the actual midstep value and the nominal midstep value at the offset point.
(4) Analog input voltages greater than the voltage applied to REF+ convert as all ones (111111111111), while input voltages less than the voltage applied to REF– convert as all zeros (000000000000).
(5) Total unadjusted error comprises linearity, zero-scale errors, and full-scale errors.
(6) Both the input address and the output codes are expressed in positive logic.

TIMING CHARACTERISTICS

over recommended operating free-air temperature range,
V_{REF+} = 5 V, I/O CLOCK frequency = 15 MHz, V_{CC} = 5 V, Load = 25 pF (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
t_{w1}	Pulse duration I/O CLOCK high or low	26.7	100000	ns
t_{su1}	Setup time DATA IN valid before I/O CLOCK rising edge (see Figure 26)	12		ns
t_{h1}	Hold time DATA IN valid after I/O CLOCK rising edge (see Figure 26)	0		ns
t_{su2}	Setup time $\overline{CS}$ low before first rising I/O CLOCK edge[1] (see Figure 27)	25		ns
t_{h2}	Hold time $\overline{CS}$ pulse duration high time (see Figure 27)	100		ns
t_{h3}	Hold time $\overline{CS}$ low after last I/O CLOCK falling edge (see Figure 27)	0		ns
t_{h4}	Hold time DATA OUT valid after I/O CLOCK falling edge (see Figure 28)	2		ns
t_{h5}	Hold time $\overline{CS}$ high after EOC rising edge when $\overline{CS}$ is toggled (see Figure 31)	0		ns
t_{d1}	Delay time $\overline{CS}$ falling edge to DATA OUT valid (MSB or LSB) (see Figure 25)	Load = 25 pF		28	ns
		Load = 10 pF		20	
t_{d2}	Delay time $\overline{CS}$ rising edge to DATA OUT high impedance (see Figure 25)		10	ns
t_{d3}	Delay time I/O CLOCK falling edge to next DATA OUT bit valid (see Figure 28)	2	20	ns
t_{d4}	Delay time last I/O CLOCK falling edge to EOC falling edge		55	ns
t_{d5}	Delay time last I/O CLOCK falling edge to $\overline{CS}$ falling edge to abort conversion		1.5	µs
t_{t1}	Transition time I/O CLOCK[1] (see Figure 28)		1	µs
t_{t2}	Transition time DATA OUT (see Figure 28)		5	ns
t_{t3}	Transition time EOC, C_L = 7 pF (see Figure 30)		2.4	ns
t_{t4}	Transition time DATA IN, $\overline{CS}$		10	µs
t_{cycle}	Total cycle time (sample, conversion and delays)[1]		[2]	µs
t_{sample}	Channel acquisition time (sample) at 1 kΩ[1] (see Figure 33 through Figure 38)	Source impedance = 25 Ω	600		ns
		Source impedance = 100 Ω	650		
		Source impedance = 500 Ω	700		
		Source impedance = 1 kΩ	1000		

(1) I/O CLOCK period = 8 × [1/(I/O CLOCK frequency)] or 12 × [1/(I/O CLOCK frequency)] or 16 × [1/(I/O CLOCK frequency)], depending on I/O format selected
(2) $t_{convert}$(max) + I/O CLOCK period (8/12/16 CLKs)

TIMING CHARACTERISTICS

over recommended operating free-air temperature range,
V_{REF+} = 2.5 V, I/O CLOCK frequency = 10 MHz, V_{CC} = 2.7 V, Load = 25 pF (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
t_{w1}	Pulse duration I/O CLOCK high or low	40	100000	ns
t_{su1}	Setup time DATA IN valid before I/O CLOCK rising edge (see Figure 26)	22		ns
t_{h1}	Hold time DATA IN valid after I/O CLOCK rising edge (see Figure 26)	0		ns
t_{su2}	Setup time $\overline{CS}$ low before first rising I/O CLOCK edge[1] (see Figure 27)	33		ns
t_{h2}	Hold time $\overline{CS}$ pulse duration high time (see Figure 27)	100		ns
t_{h3}	Hold time $\overline{CS}$ low after last I/O CLOCK falling edge (see Figure 27)	0		ns
t_{h4}	Hold time DATA OUT valid after I/O CLOCK falling edge (see Figure 28)	2		ns
t_{h5}	Hold time $\overline{CS}$ high after EOC rising edge when $\overline{CS}$ is toggled (see Figure 31)	0		ns
t_{d1}	Delay time $\overline{CS}$ falling edge to DATA OUT valid (MSB or LSB) (see Figure 25)	Load = 25 pF		30	ns
		Load = 10 pF		22	
t_{d2}	Delay time $\overline{CS}$ rising edge to DATA OUT high impedance (see Figure 25)		10	ns
t_{d3}	Delay time I/O CLOCK falling edge to next DATA OUT bit valid (see Figure 28)	2	33	ns
t_{d4}	Delay time last I/O CLOCK falling edge to EOC falling edge		75	ns
t_{d5}	Delay time last I/O CLOCK falling edge to $\overline{CS}$ falling edge to abort conversion		1.5	µs
t_{t1}	Transition time I/O CLOCK[1] (see Figure 28)		1	µs
t_{t2}	Transition time DATA OUT (see Figure 28)		5	ns
t_{t3}	Transition time EOC, C_L = 7 pF (see Figure 30)		4	ns
t_{t4}	Transition time DATA IN, $\overline{CS}$		10	µs
t_{cycle}	Total cycle time (sample, conversion and delays)[1]		[2]	µs
t_{sample}	Channel acquisition time (sample), at 1 kΩ[1] (see Figure 33 through Figure 38)	Source impedance = 25 Ω	800		ns
		Source impedance = 100 Ω	850		
		Source impedance = 500 Ω	1000		
		Source impedance = 1 kΩ	1600		

(1) I/O CLOCK period = 8 × [1/(I/O CLOCK frequency)] or 12 × [1/(I/O CLOCK frequency)] or 16 × [1/(I/O CLOCK frequency)], depending on I/O format selected
(2) $t_{convert}$(max) + I/O CLOCK period (8/12/16 CLKs)

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE
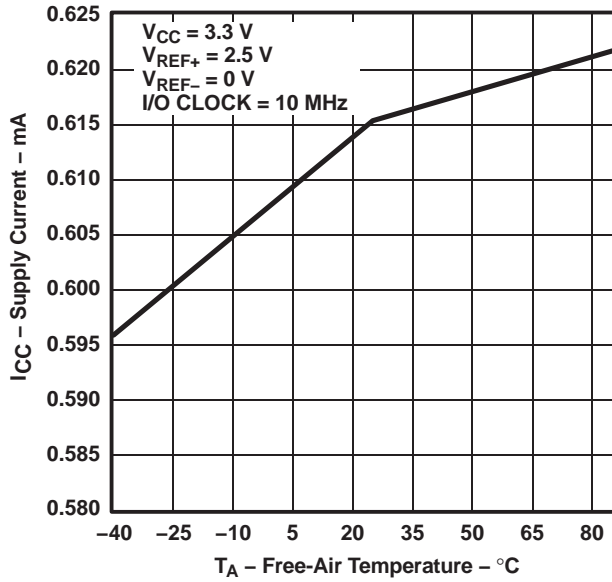
Figure 1.

EXTERNAL REFERENCE CURRENT
vs
FREE-AIR TEMPERATURE
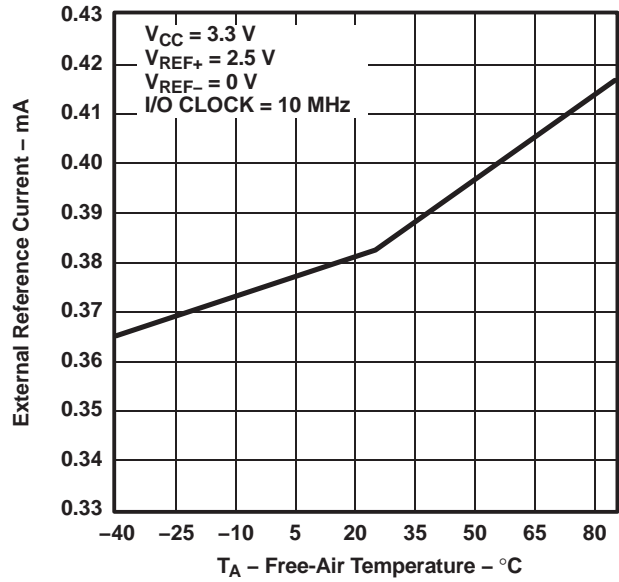
Figure 2.

SOFTWARE POWER DOWN
vs
FREE-AIR TEMPERATURE
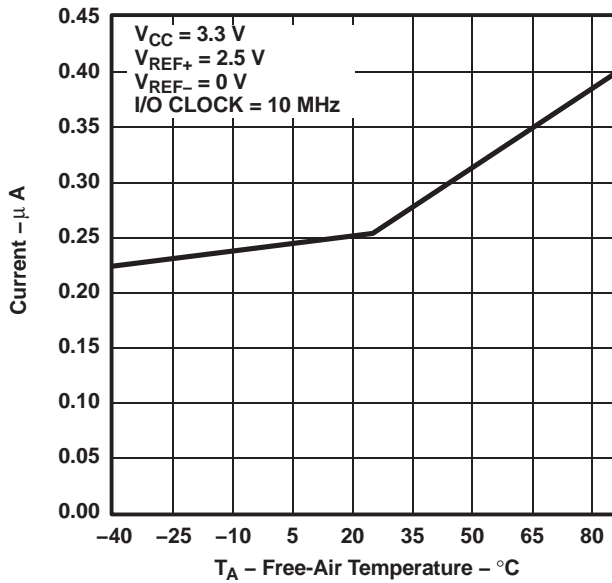
Figure 3.

AUTO POWER DOWN
vs
FREE-AIR TEMPERATURE

Figure 4.

Submit Documentation Feedback

9
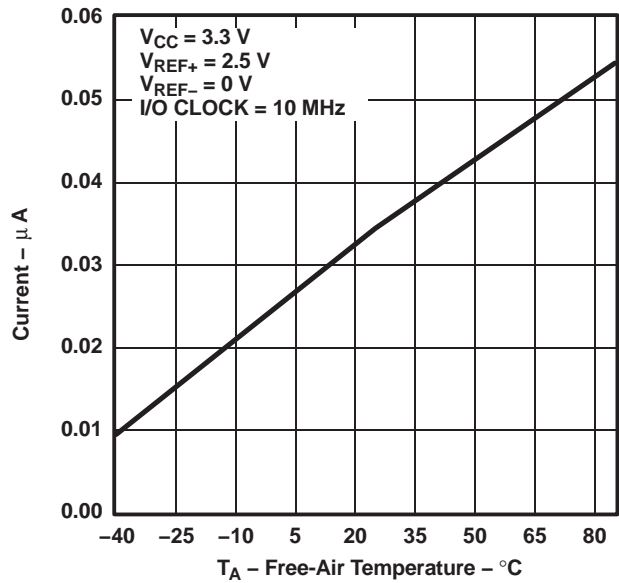
TYPICAL CHARACTERISTICS (continued)

MAXIMUM DIFFERENTIAL NONLINEARITY vs FREE-AIR TEMPERATURE

V_{CC} = 2.7 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

Maximum Differential Nonlinearity – LSB

T_A – Free-Air Temperature – °C
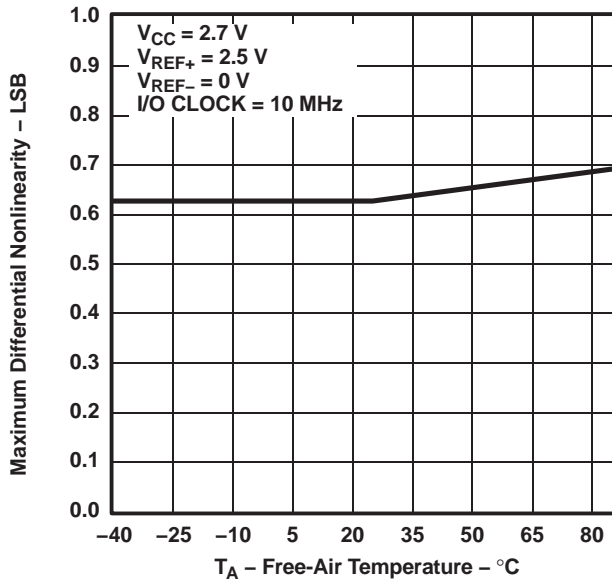
Figure 5.

MINIMUM DIFFERENTIAL NONLINEARITY vs FREE-AIR TEMPERATURE

V_{CC} = 2.7 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

Minimum Differential Nonlinearity – LSB

T_A – Free-Air Temperature – °C
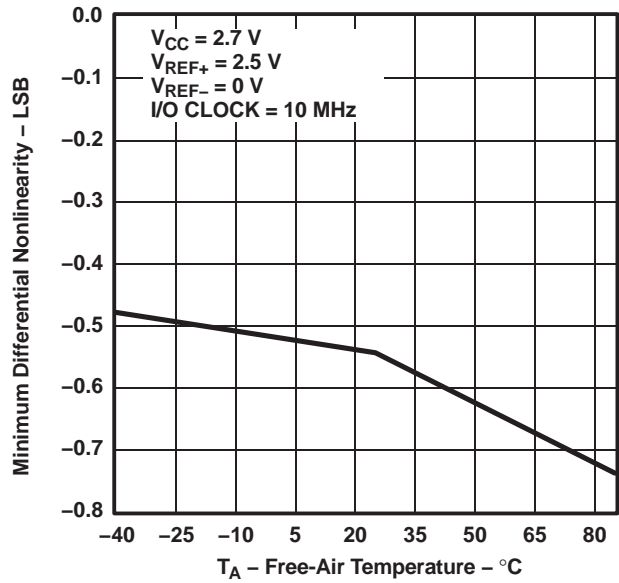
Figure 6.

MAXIMUM INTEGRAL NONLINEARITY vs FREE-AIR TEMPERATURE

V_{CC} = 2.7 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

Maximum Integral Nonlinearity – LSB

T_A – Free-Air Temperature – °C
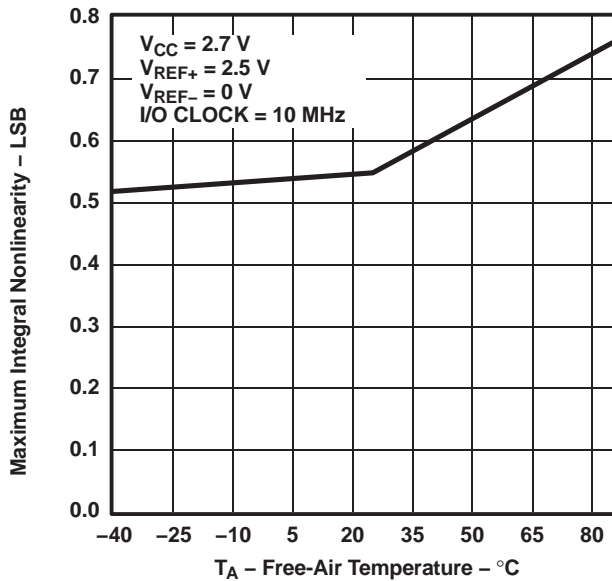
Figure 7.

MINIMUM INTEGRAL NONLINEARITY vs FREE-AIR TEMPERATURE

V_{CC} = 2.7 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

Minimum Integral Nonlinearity – LSB

T_A – Free-Air Temperature – °C
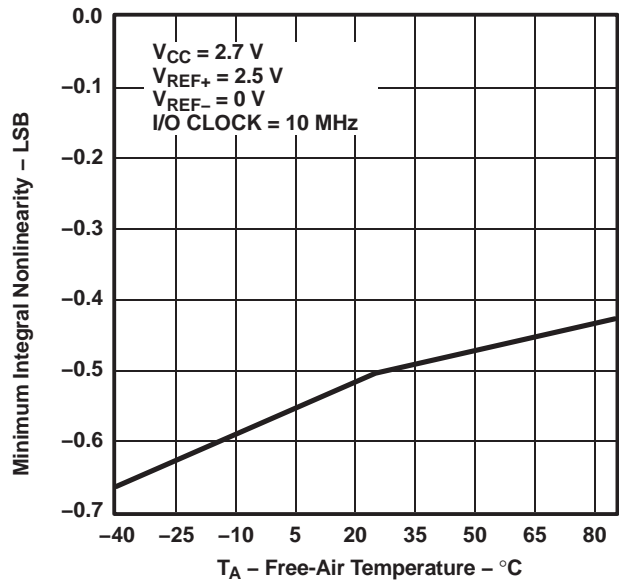
Figure 8.

TYPICAL CHARACTERISTICS (continued)

DIFFERENTIAL NONLINEARITY
vs
DIGITAL OUTPUT CODE

Figure 9.

INTEGRAL NONLINEARITY
vs
DIGITAL OUTPUT CODE

Figure 10.

TYPICAL CHARACTERISTICS (continued)

OFFSET ERROR
vs
FREE-AIR TEMPERATURE

V_{CC} = 3.3 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

E$_O$ – Offset Error – mV

T$_A$ – Free-Air Temperature – °C

Figure 11.

GAIN ERROR
vs
FREE-AIR TEMPERATURE

V_{CC} = 3.3 V
V_{REF+} = 2.5 V
V_{REF-} = 0 V
I/O CLOCK = 10 MHz

E$_G$ – Gain Error – mV

T$_A$ – Free-Air Temperature – °C

Figure 12.

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

I$_{CC}$ – Supply Current – mA

T$_A$ – Free-Air Temperature – °C

Figure 13.

EXTERNAL REFERENCE CURRENT
vs
FREE-AIR TEMPERATURE

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

External Reference Current – mA

T$_A$ – Free-Air Temperature – °C

Figure 14.

Product Folder Link(s): *TLV2553-Q1*

TYPICAL CHARACTERISTICS (continued)

**SOFTWARE POWER DOWN
vs
FREE-AIR TEMPERATURE**

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

Current – μA

T_A – Free-Air Temperature – °C
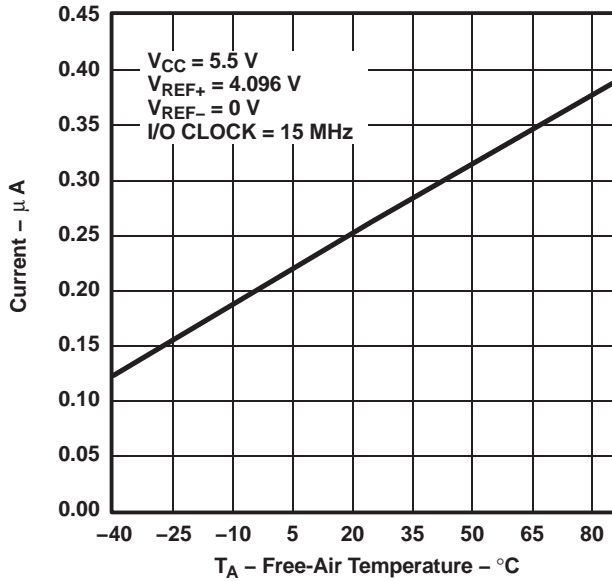
Figure 15.

**AUTO POWER DOWN
vs
FREE-AIR TEMPERATURE**

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

Current – μA

T_A – Free-Air Temperature – °C
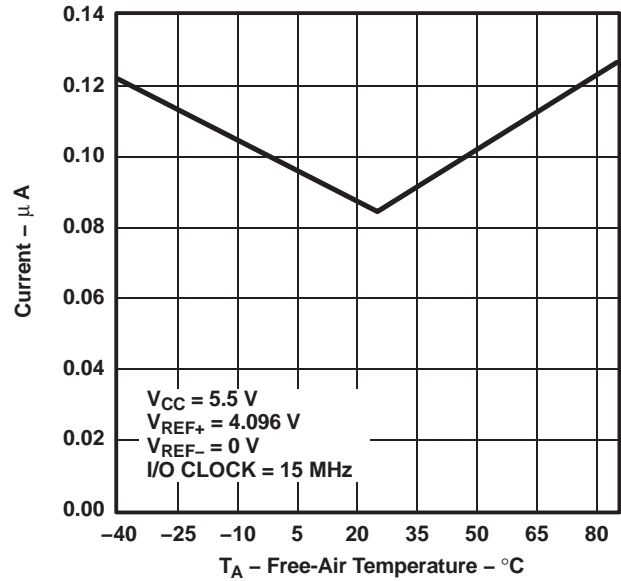
Figure 16.

**MAXIMUM DIFFERENTIAL NONLINEARITY
vs
FREE-AIR TEMPERATURE**

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

Maximum Differential Nonlinearity – LSB

T_A – Free-Air Temperature – °C
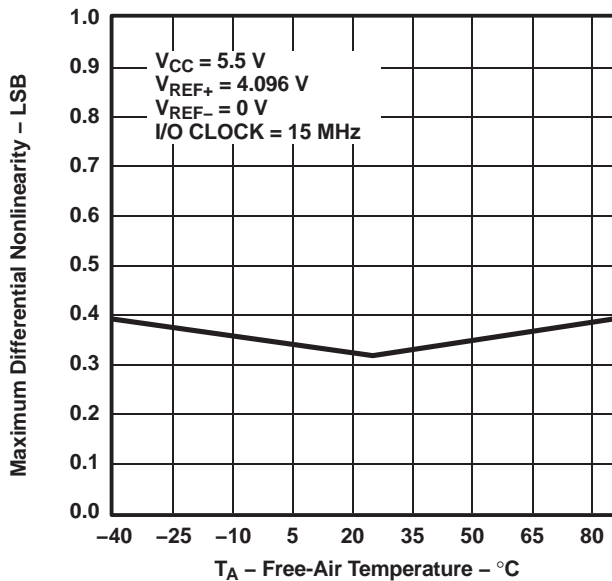
Figure 17.

**MINIMUM DIFFERENTIAL NONLINEARITY
vs
FREE-AIR TEMPERATURE**

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
V_{REF-} = 0 V
I/O CLOCK = 15 MHz

Minimum Differential Nonlinearity – LSB

T_A – Free-Air Temperature – °C
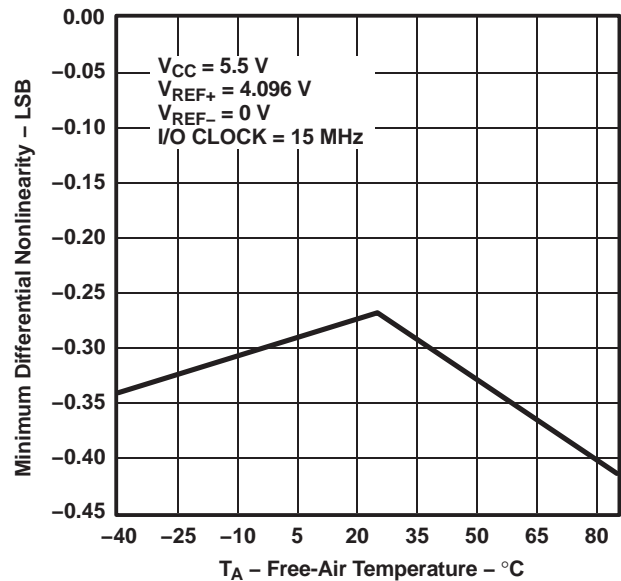
Figure 18.

TYPICAL CHARACTERISTICS (continued)

MAXIMUM INTEGRAL NONLINEARITY
vs
FREE-AIR TEMPERATURE

Figure 19.

MINIMUM INTEGRAL NONLINEARITY
vs
FREE-AIR TEMPERATURE

Figure 20.

DIFFERENTIAL NONLINEARITY
vs
DIGITAL OUTPUT CODE

Figure 21.

Product Folder Link(s): TLV2553-Q1
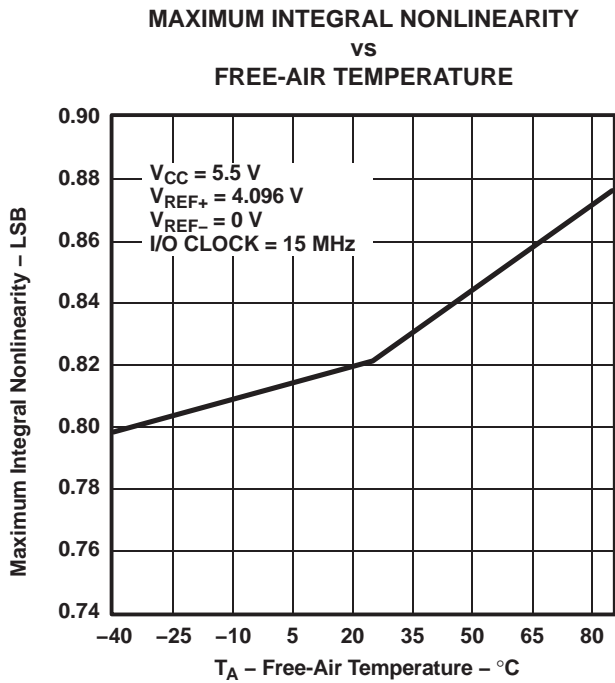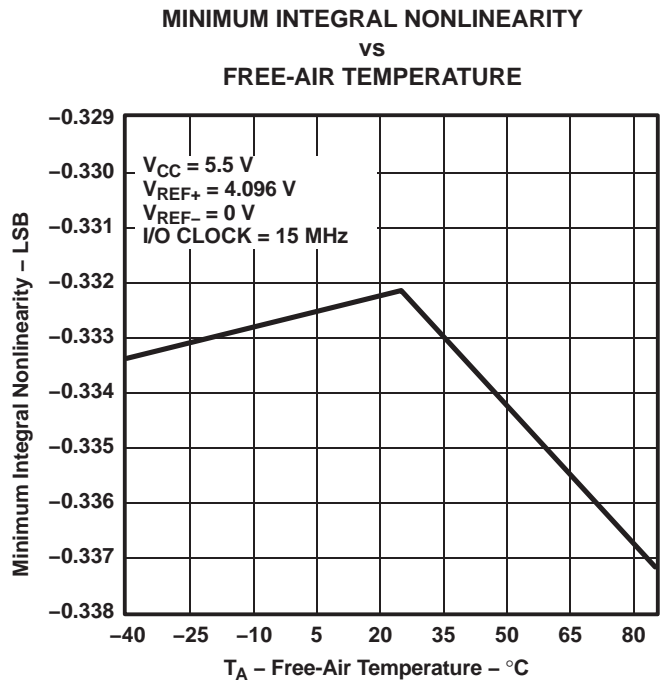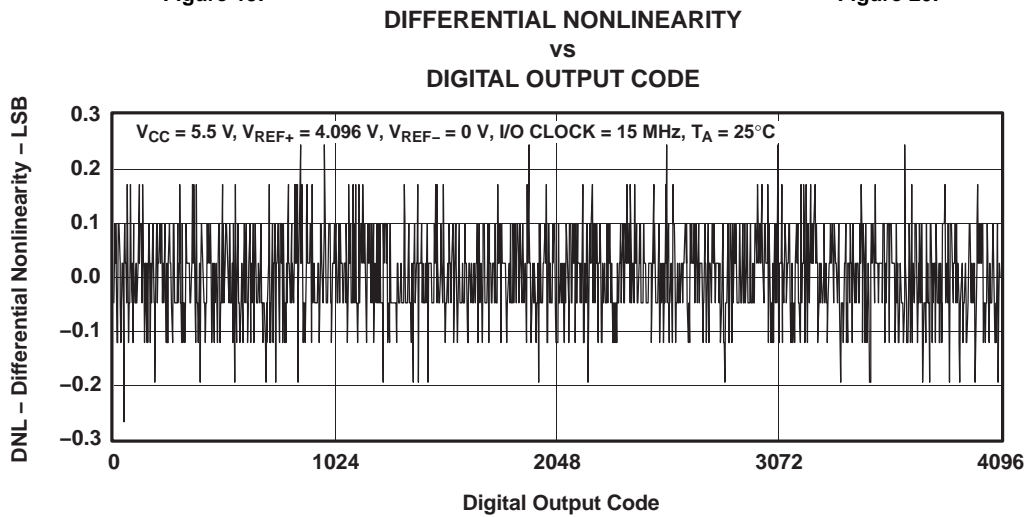
TYPICAL CHARACTERISTICS (continued)

INTEGRAL NONLINEARITY
vs
DIGITAL OUTPUT CODE

V_{CC} = 5.5 V, V_{REF+} = 4.096 V, $V_{REF−}$ = 0 V, I/O CLOCK = 15 MHz, T_A = 25°C
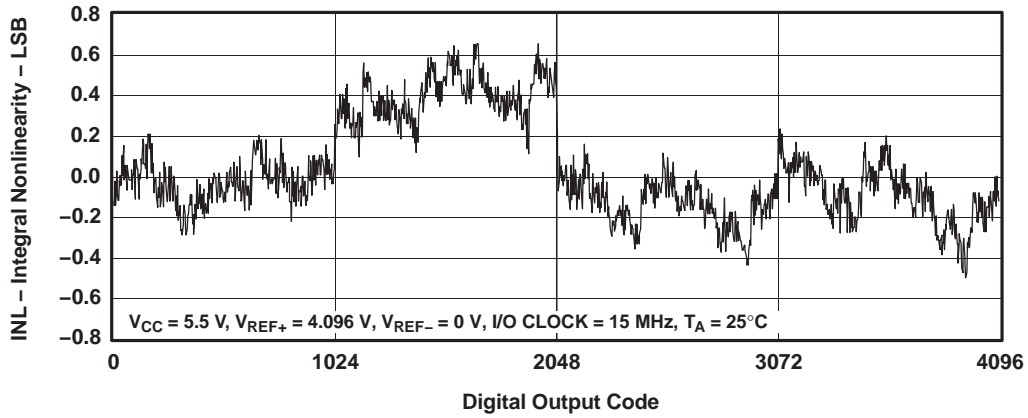
Figure 22.

OFFSET ERROR
vs
FREE-AIR TEMPERATURE

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
$V_{REF−}$ = 0 V
I/O CLOCK = 15 MHz
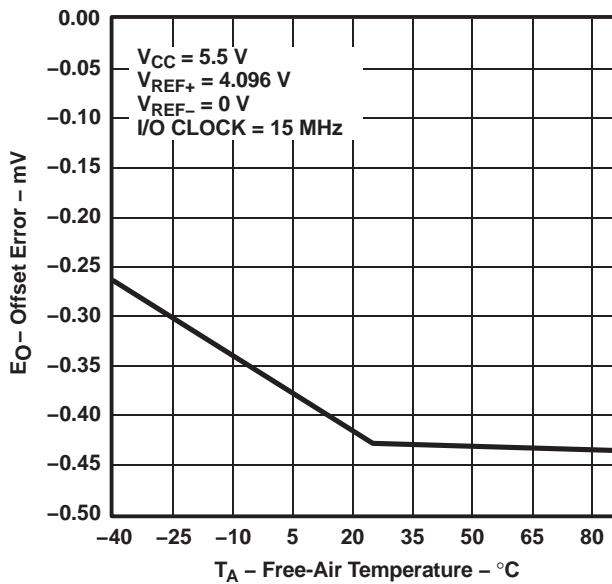
Figure 23.

GAIN ERROR
vs
FREE-AIR TEMPERATURE

V_{CC} = 5.5 V
V_{REF+} = 4.096 V
$V_{REF−}$ = 0 V
I/O CLOCK = 15 MHz

Figure 24.

TEXAS
INSTRUMENTS
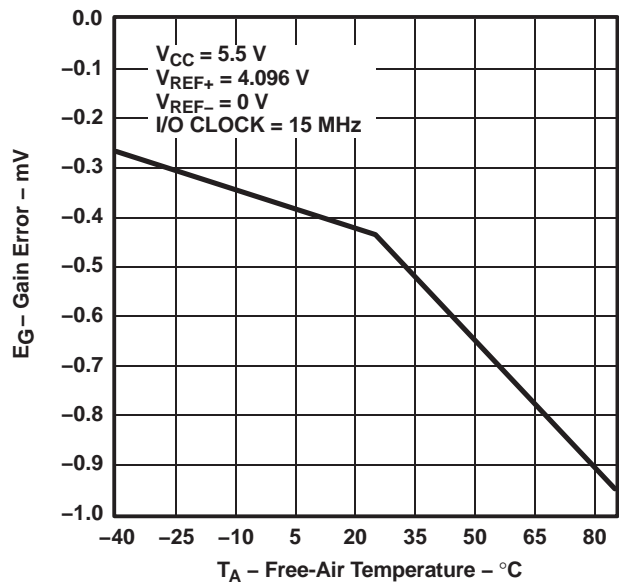
Parameter Measurement Information
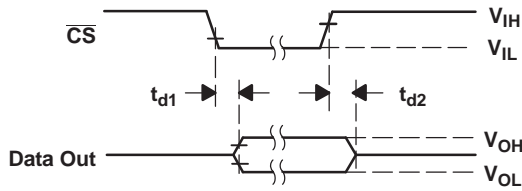
Figure 25. DATA OUT to Hi-Z Voltage Waveforms
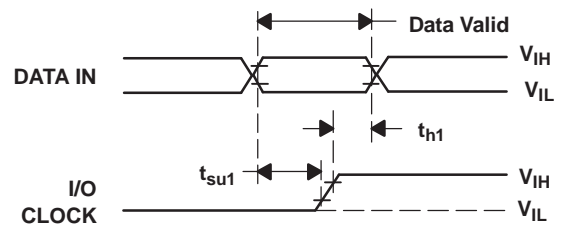
Figure 26. DATA IN and I/O CLOCK Voltage
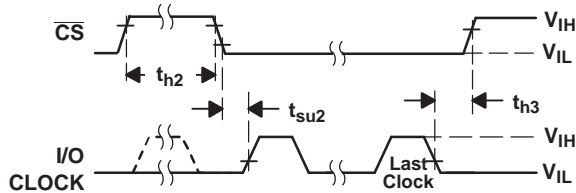
Figure 27. $\overline{CS}$ and I/O CLOCK Voltage Waveforms
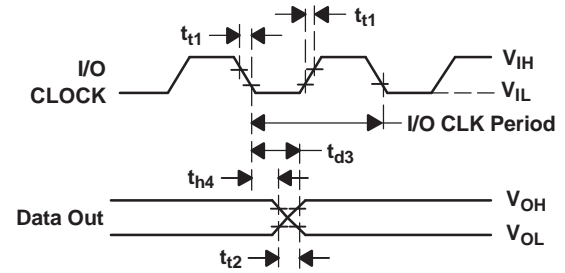
Figure 28. I/O CLOCK and DATA OUT Voltage Waveforms
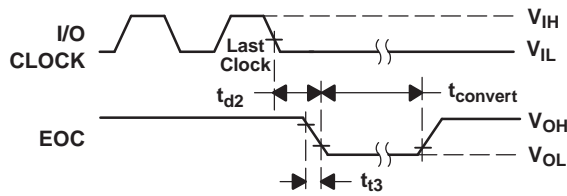
Figure 29. I/O CLOCK and EOC Voltage Waveforms
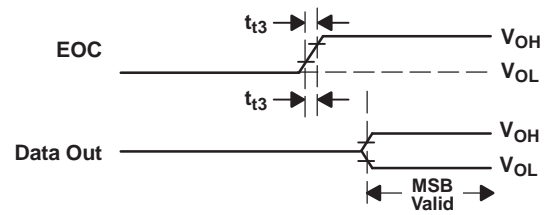
Figure 30. EOC and DATA OUT Voltage Waveforms
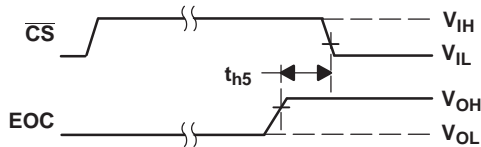
Figure 31. $\overline{CS}$ and EOC Waveforms
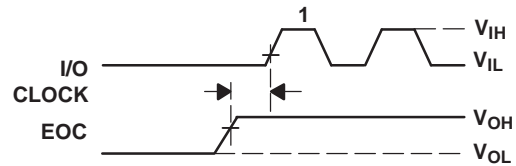
Figure 32. I/O CLOCK and DATA OUT Voltage

Product Folder Link(s): *TLV2553-Q1*

Parameter Measurement Information (continued)
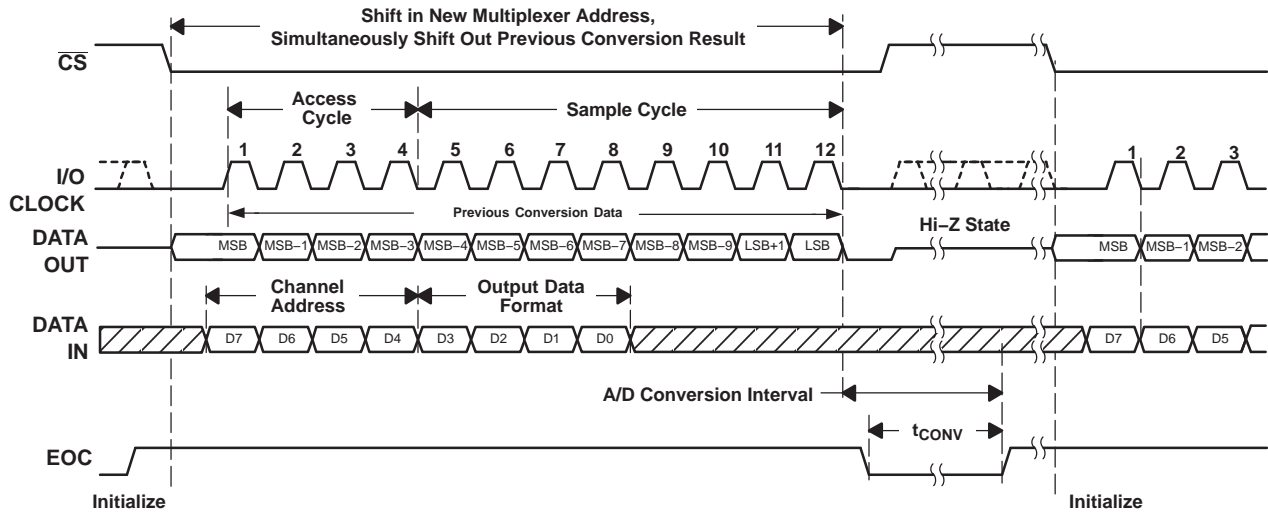
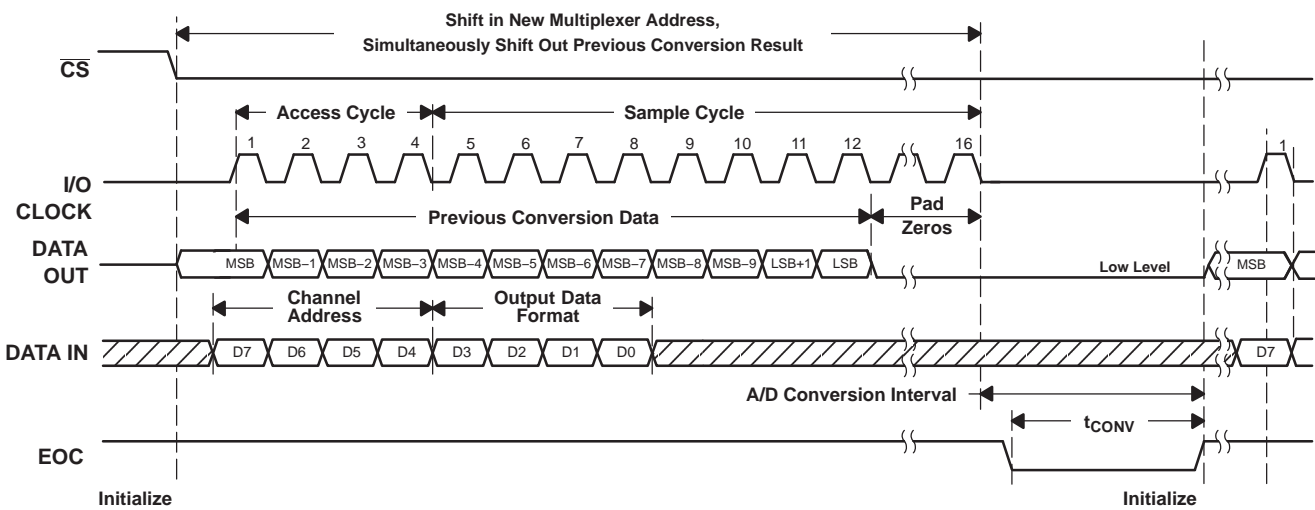**Figure 33. Timing for 12-Clock Transfer Using CS With DATA OUT Set for MSB First**
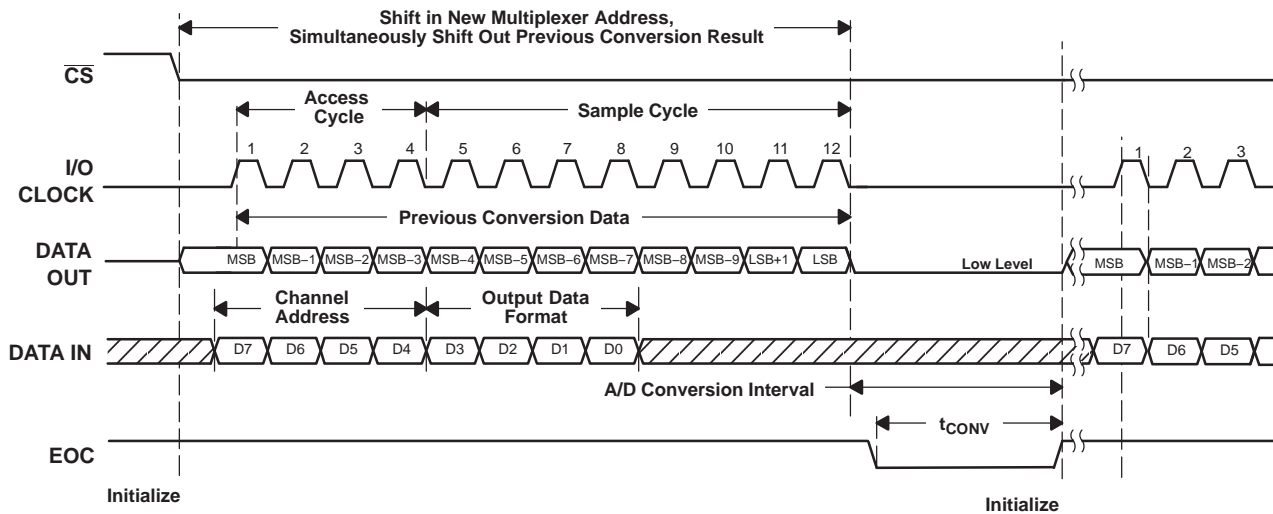
NOTE: To minimize errors caused by noise at CS, the internal circuitry waits for a setup time after the CS falling edge before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum CS setup time has elapsed.

Figure 34. Timing for 12-Clock Transfer Not Using CS With DATA OUT Set for MSB First

Parameter Measurement Information (continued)
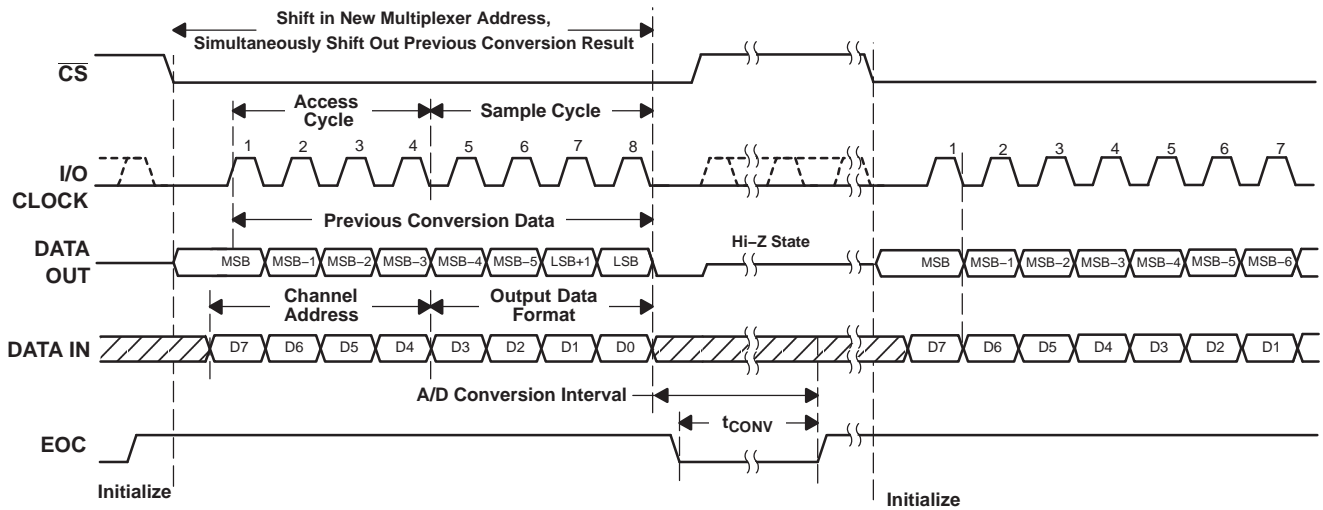
Figure 35. Timing for 8-Clock Transfer Using $\overline{\text{CS}}$ With DATA OUT Set for MSB First
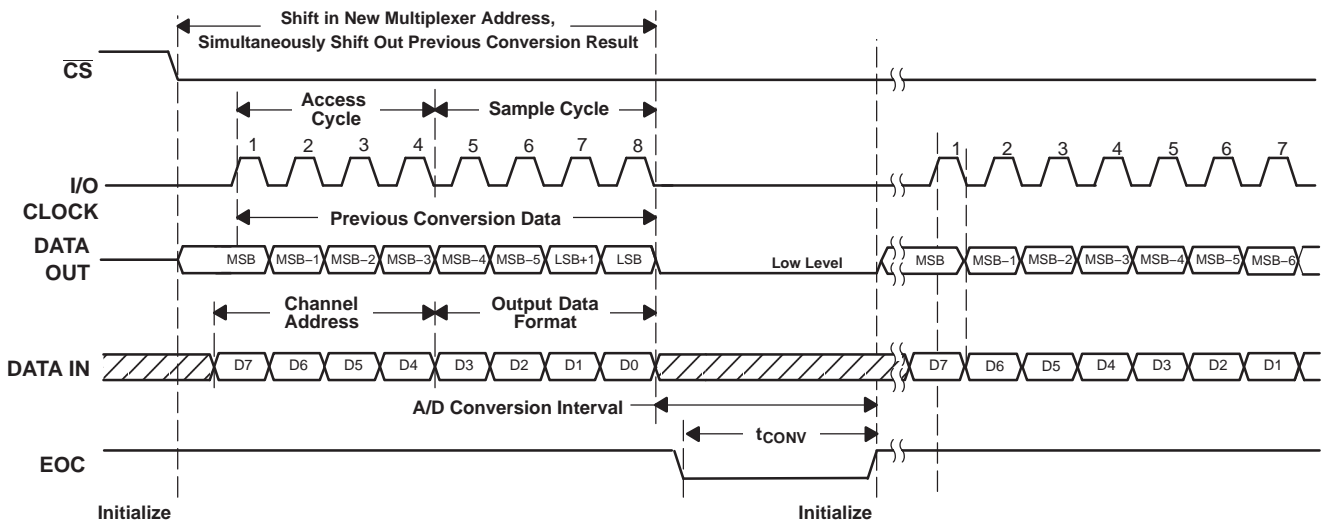
NOTE: To minimize errors caused by noise at $\overline{\text{CS}}$, the internal circuitry waits for a setup time after the $\overline{\text{CS}}$ falling edge before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum $\overline{\text{CS}}$ setup time has elapsed.

Figure 36. Timing for 8-Clock Transfer Not Using $\overline{\text{CS}}$ With DATA OUT Set for MSB First

Product Folder Link(s): *TLV2553-Q1*

Parameter Measurement Information (continued)

Figure 37. Timing for 16-Clock Transfer Using $\overline{CS}$ With DATA OUT Set for MSB First

NOTE: To minimize errors caused by noise at $\overline{CS}$, the internal circuitry waits for a setup time after the $\overline{CS}$ falling edge before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum $\overline{CS}$ setup time has elapsed.

Figure 38. Timing for 16-Clock Transfer Not Using $\overline{CS}$ With DATA OUT Set for MSB First

PRINCIPLES OF OPERATION

Detailed Description

Initially, with chip select ($\overline{CS}$) high, I/O CLOCK and DATA IN are disabled and DATA OUT is in the high-impedance state. $\overline{CS}$ going low begins the conversion sequence by enabling I/O CLOCK and DATA IN and removes DATA OUT from the high-impedance state. The input data is an 8-bit data stream consisting of a 4-bit address or command (D7–D4) and a 4-bit configuration data (D3–D0). Configuration register 1 (CFGR1), which controls output data format configuration, consists of a 2-bit data length select (D3–D2), an output MSB or LSB first bit (D1), and a unipolar or bipolar output select bit (D0) that are applied to any command (from DATA IN) except for command 1111b. The I/O CLOCK sequence applied to the I/O CLOCK terminal transfers this data to the input data register. During this transfer, the I/O CLOCK sequence also shifts the previous conversion result from the output data register to DATA OUT. I/O CLOCK receives the input sequence of 8, 12, or 16 clock cycles long depending on the data-length selection in the input data register. Sampling of the analog input begins on the fourth falling edge of the input I/O CLOCK sequence and is held after the last falling edge of the I/O CLOCK sequence. The last falling edge of the I/O CLOCK sequence also takes EOC low and begins the conversion.

Converter Operation

The operation of the converter is organized as a succession of three distinct cycles: 1) the data I/O cycle, 2) the sampling cycle, and 3) the conversion cycle. The first two are partially overlapped.

Data I/O Cycle

The data I/O cycle is defined by the externally provided I/O CLOCK and lasts 8, 12, or 16 clock periods, depending on the selected output data length. During the I/O cycle, the following two operations take place simultaneously. An 8-bit data stream consisting of address/command and configuration information is provided to DATA IN. This data is shifted into the device on the rising edge of the first eight I/O CLOCK clocks. DATA INPUT is ignored after the first eight clocks during 12- or 16-clock I/O transfers. The data output, with a length of 8, 12, or 16 bits, is provided serially on DATA OUT. When $\overline{CS}$ is held low, the first output data bit occurs on the rising edge of EOC. When $\overline{CS}$ is toggled between conversions, the first output data bit occurs on the falling edge of $\overline{CS}$. This data is the result of the previous conversion period, and after the first output data bit, each succeeding bit is clocked out on the falling edge of each succeeding I/O CLOCK.

Sampling Cycle

During the sampling cycle, one of the analog inputs is internally connected to the capacitor array of the converter to store the analog input signal. The converter starts sampling the selected input immediately after the four address/command bits have been clocked into the input data register. Sampling starts on the fourth falling edge of I/O CLOCK. The converter remains in the sampling mode until the eighth, twelfth, or sixteenth falling edge of the I/O CLOCK depending on the data-length selection.

After the 8-bit data stream has been clocked in, DATA IN should be held at a fixed digital level until EOC goes high (indicating that the conversion is complete) to maximize the sampling accuracy and minimize the influence of external digital noise.

Conversion Cycle

A conversion cycle is started only after the I/O cycle is completed, which minimizes the influence of external digital noise on the accuracy of the conversion. This cycle is transparent to the user because it is controlled by an internal clock (oscillator). The total conversion time is equal to 13.5 OSC clocks plus a small delay (~25 ns) to start the OSC. During the conversion period, the device performs a successive-approximation conversion on the analog input voltage.

EOC goes low at the start of the conversion cycle and goes high when the conversion is complete and the output data register is latched. After EOC goes low, the analog input can be changed without affecting the conversion result. Since the delay from the falling edge of the last I/O CLOCK to the falling edge of EOC is fixed, any time-varying analog input signals can be digitized at a fixed rate without introducing systematic harmonic distortion or noise due to timing uncertainty.

Product Folder Link(s): *TLV2553-Q1*

Power Up and Initialization

After power up, $\overline{CS}$ must be taken from high to low to begin an I/O cycle. The EOC pin is initially high, and the configuration register is set to all zeroes. The contents of the output data register are random, and the first conversion result should be ignored. To initialize during operation, $\overline{CS}$ is taken high and is then returned low to begin the next I/O cycle. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

Table 1. Operational Terminology

Current (N) I/O cycle	The entire I/O CLOCK sequence that transfers address and control data into the data register and clocks the digital result from the previous conversion from DATA OUT
Current (N) conversion cycle	The conversion cycle starts immediately after the current I/O cycle. The end of the current I/O cycle is the last clock falling edge in the I/O CLOCK sequence. The current conversion result is loaded into the output register when conversion is complete.
Current (N) conversion result	The current conversion result is serially shifted out on the next I/O cycle.
Previous (N – 1) conversion cycle	The conversion cycle just prior to the current I/O cycle
Next (N + 1) I/O cycle	The I/O period that follows the current conversion cycle

Example

In 12-bit mode, the result of the current conversion cycle is a 12-bit serial-data stream clocked out during the next I/O cycle. The current I/O cycle must be exactly 12 bits long to maintain synchronization, even when this corrupts the output data from the previous conversion. The current conversion is begun immediately after the twelfth falling edge of the current I/O cycle.

Data Input

The data input is internally connected to an 8-bit serial-input address and control register. The register defines the operation of the converter and the output data length. The host provides the input data byte with the MSB first. Each data bit is clocked in on the rising edge of the I/O CLOCK sequence (see Table 2 for the data input-register format).

Table 2. Command Set (CMR) and Configuration

SDI D[7:4]		COMMAND
BINARY	HEX	
0000	0	SELECT analog input channel 0
0001	1	SELECT analog input channel 1
0010	2	SELECT analog input channel 2
0011	3	SELECT analog input channel 3
0100	4	SELECT analog input channel 4
0101	5	SELECT analog input channel 5
0110	6	SELECT analog input channel 6
0111	7	SELECT analog input channel 7
1000	8	SELECT analog input channel 8
1001	9	SELECT analog input channel 9
1010	A	SELECT analog input channel 10
1011	B	SELECT TEST, Voltage = $(V_{REF+} + V_{REF-})/2$
1100	C	SELECT TEST, Voltage = REFM
1101	D	SELECT TEST, Voltage = REFP
1110	E	SW POWERDOWN (analog + reference)
1111	F	Reserved

CFGR1 SDI D[3:0]	CONFIGURATION
D[3:2]	01: 8-bit output length X0: 12-bit output length[1] 11: 16-bit output length
D1	0: MSB out first 1: LSB out first
D0	0: Unipolar binary 1: Bipolar 2s complement

(1)   Select 12-bit output mode to achieve 200-KSPS sampling rate.

Data Input − Address/Command Bits

The four MSBs (D7–D4) of the input data register are the address or command. These can be used to address one of the 11 input channels, address one of three reference-test voltages, or activate software power-down mode. All address/command bits affect the current conversion, which is the conversion that immediately follows the current I/O cycle. They also have access to CFGR1 except for command 1111b, which is reserved.

Data Output Length

CFGR1 bits (D3 and D2) of the data register select the output data length. The data-length selection is valid for the current I/O cycle (the cycle in which the data is read). The data-length selection, being valid for the current I/O cycle, allows device start-up without losing I/O synchronization. A data length of 8, 12, or 16 bits can be selected. Since the converter has 12-bit resolution, a data length of 12 bits is suggested.

With D3 and D2 set to 00 or 10, the device is in the 12-bit data-length mode and the result of the current conversion is output as a 12-bit serial data stream during the next I/O cycle. The current I/O cycle must be exactly 12 bits long for proper synchronization, even when this means corrupting the output data from a previous conversion. The current conversion is started immediately after the twelfth falling edge of the current I/O cycle.

With bits D3 and D2 set to 11, the 16-bit data-length mode is selected, which allows convenient communication with 16-bit serial interfaces. In the 16-bit mode, the result of the current conversion is output as a 16-bit serial data stream during the next I/O cycle with the four LSBs always reset to 0 (pad bits). The current I/O cycle must be exactly 16 bits long to maintain synchronization even when this means corrupting the output data from the previous conversion. The current conversion is started immediately after the sixteenth falling edge of the current I/O cycle.

With bits D3 and D2 set to 01, the 8-bit data-length mode is selected, which allows fast communication with 8-bit serial interfaces. In the 8-bit mode, the result of the current conversion is output as an 8-bit serial data stream during the next I/O cycle. The current I/O cycle must be exactly eight bits long to maintain synchronization, even when this means corrupting the output data from the previous conversion. The four LSBs of the conversion result are truncated and discarded. The current conversion is started immediately after the eighth falling edge of the current I/O cycle.

Since the D3 and D2 register settings take effect on the I/O cycle when the data length is programmed, there can be a conflict with the previous cycle if the data-word length was changed. This may occur when the data format is selected to be least significant bit first, since at the time the data length change becomes effective (six rising edges of I/O CLOCK), the previous conversion result has already started shifting out. In actual operation, when different data lengths are required within an application and the data length is changed between two conversions, no more than one conversion result can be corrupted and only when it is shifted out in LSB-first format.

LSB Out First

D1 in the CFGR1 controls the direction of the output (binary) data transfer. When D1 is reset to 0, the conversion result is shifted out MSB first. When set to 1, the data is shifted out LSB first. Selection of MSB first or LSB first always affects the next I/O cycle and not the current I/O cycle. When changing from one data direction to another, the current I/O cycle is never disrupted.

Bipolar Output Format

D0 in the CFGR1 controls the binary data format used to represent the conversion result. When D0 is cleared to 0, the conversion result is represented as unipolar (unsigned binary) data. Nominally, the conversion result of an input voltage equal to or less than V_{REF-} is a code with all zeros (000...0) and the conversion result of an input voltage equal to or greater than V_{REF+} is a code of all ones (111...1). The conversion result of $(V_{REF+} + V_{REF-})/2$ is a code of a one followed by zeros (100...0).

When D0 is set to 1, the conversion result is represented as bipolar (signed binary) data. Nominally, conversion of an input voltage equal to or less than V_{REF-} is a code of a one followed by zeros (100...0), and the conversion of an input voltage equal to or greater than V_{REF+} is a code of a zero followed by all ones (011...1). The conversion result of $(V_{REF+} + V_{REF-})/2$ is a code of all zeros (000...0). The MSB is interpreted as the sign bit. The bipolar data format is related to the unipolar format in that the MSBs are always each other's complement.

Selection of the unipolar or bipolar format always affects the current conversion cycle, and the result is output during the next I/O cycle. When changing between unipolar and bipolar formats, the data output during the current I/O cycle is not affected.

Reference

An external reference can be used through two reference input pins, REF+ and REF–. The voltage levels applied to these pins establish the upper and lower limits of the analog inputs to produce a full-scale and zero-scale reading respectively. The values of REF+, REF–, and the analog input should not exceed the positive supply or be lower than GND consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ and at zero when the input signal is equal to or lower than REF–.
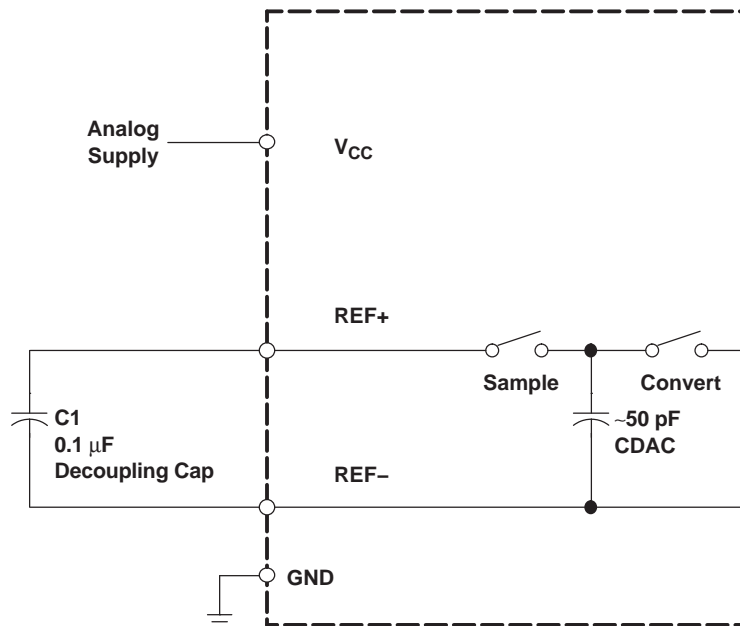
Figure 39. Reference Block

EOC Output

Pin 19 outputs the status of the ADC conversion. When programmed as EOC, the output indicates the beginning and the end of conversion. In the reset state, EOC is always high. During the sampling period (beginning after the fourth falling edge of the I/O CLOCK sequence), EOC remains high until the internal sampling switch of the converter is safely opened. The opening of the sampling switch occurs after the eighth, twelfth, or sixteenth I/O CLOCK falling edge, depending on the data-length selection in the input data register. After the EOC signal goes low, the analog input signal can be changed without affecting the conversion result.

The EOC signal goes high again after the conversion is completed and the conversion result is latched into the output data register. The rising edge of EOC returns the converter to a reset state and a new I/O cycle begins. On the rising edge of EOC, the first bit of the current conversion result is on DATA OUT when $\overline{CS}$ is low. When $\overline{CS}$ is toggled between conversions, the first bit of the current conversion result occurs on DATA OUT at the falling edge of $\overline{CS}$.

Chip-Select Input ($\overline{CS}$)

$\overline{CS}$ enables and disables the device. During normal operation, $\overline{CS}$ should be low. Although the use of $\overline{CS}$ is not necessary to synchronize a data transfer, it can be brought high between conversions to coordinate the data transfer of several devices sharing the same bus.

When $\overline{CS}$ is brought high, the serial-data output is immediately brought to the high-impedance state, releasing its output data line to other devices that may share it. After an internally generated debounce time, I/O CLOCK is inhibited, thus preventing any further change in the internal state.

When $\overline{CS}$ is subsequently brought low again, the device is reset. $\overline{CS}$ must be held low for an internal debounce time before the reset operation takes effect. After $\overline{CS}$ is debounced low, I/O CLOCK must remain inactive (low) for a minimum time before a new I/O cycle can start.

$\overline{CS}$ can interrupt any ongoing data transfer or any ongoing conversion. When $\overline{CS}$ is debounced low long enough before the end of the current conversion cycle, the previous conversion result is saved in the internal output buffer and shifted out during the next I/O cycle.

When $\overline{CS}$ is held low continuously for multiple cycles, the first data bit of the newly completed conversion occurs on DATA OUT on the rising edge of EOC. Note that the first cycle in the series still requires a transition $\overline{CS}$ from high to low. When a new conversion is started after the last falling edge of I/O CLOCK, EOC goes low and the serial output is forced low until EOC goes high again.

When $\overline{CS}$ is toggled between conversions, the first data bit occurs on DATA OUT on the falling edge of $\overline{CS}$. On each subsequent falling edge of I/O CLOCK after the first data bit appears, the data is changed to the next bit in the serial conversion result until the required number of bits has been output.

Power-Down Features

When command (D7–D4) 1110b is clocked into the input data register during the first four I/O CLOCK cycles, the software power-down mode is selected. Software power down is activated on the falling edge of the fourth I/O CLOCK pulse.

During software power-down, all internal circuitry is put in a low-current standby mode. No conversions is performed. The internal output buffer keeps the previous conversion cycle data results, provided that all digital inputs are held above V_{CC} − 0.5 V or below 0.5 V. The I/O logic remains active so the current I/O cycle must be completed even when the power-down mode is selected. Upon power-on reset and before the first I/O cycle, the converter normally begins in the power-down mode. The device remains in the software power-down mode until a valid input address (other than command 1110b or 1111b) is clocked in. Upon completion of that I/O cycle, a normal conversion is performed with the results being shifted out during the next I/O cycle.

The ADC also has an auto power-down mode. This is transparent to users. The ADC gets into auto power-down within one I/O CLOCK cycle after the conversion is complete and resumes, with a small delay, after an active $\overline{CS}$ is sent to the ADC. The resumption is fast enough to be used between cycles.

Analog MUX

The 11 analog inputs, 3 internal voltages, and power-down mode are selected by the input multiplexer according to the input addresses shown in Table 2. The input multiplexer is a break-before-make type to reduce input-to-input noise rejection resulting from channel switching. Sampling of the analog input starts on the falling edge of the fourth I/O CLOCK and continues for the remaining I/O CLOCK pulses. The sample is held on the falling edge of the last I/O CLOCK pulse. The three internal test inputs are applied to the multiplexer, then sampled and converted in the same manner as the external analog inputs. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
TLV2553IDWRQ1	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TLV2553-Q1 :
● Catalog: TLV2553

NOTE: Qualified Version Definitions:
   ● Catalog - TI's standard catalog product

DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

$\frac{0.512\ (13,00)}{0.496\ (12,60)}$

20   11

$\frac{0.419\ (10,63)}{0.393\ (9,97)}$

$\frac{0.299\ (7,60)}{0.291\ (7,40)}$

1   10

Pin 1
Index Area

0.050 (1,27)

$\frac{0.020\ (0,51)}{0.012\ (0,31)}$

⊕ | 0.010 (0,25) Ⓜ

0.104 (2,65) Max

$\frac{0.012\ (0,30)}{0.004\ (0,10)}$

$\frac{0.013\ (0,33)}{0.008\ (0,20)}$

⌒ | 0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

$\frac{0.050\ (1,27)}{0.016\ (0,40)}$

4040000−4/G 01/11

NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D. Falls within JEDEC MS−013 variation AC.

TEXAS INSTRUMENTS
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DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

20x0,6

18x1,27

20x0,55

18x1,27

20x1,95

9,4

9,4

Non Solder Mask Define Pad

0,6

Solder Mask Opening
(Note E)

2,0

Pad Geometry
(Note C)

0,07
All Around
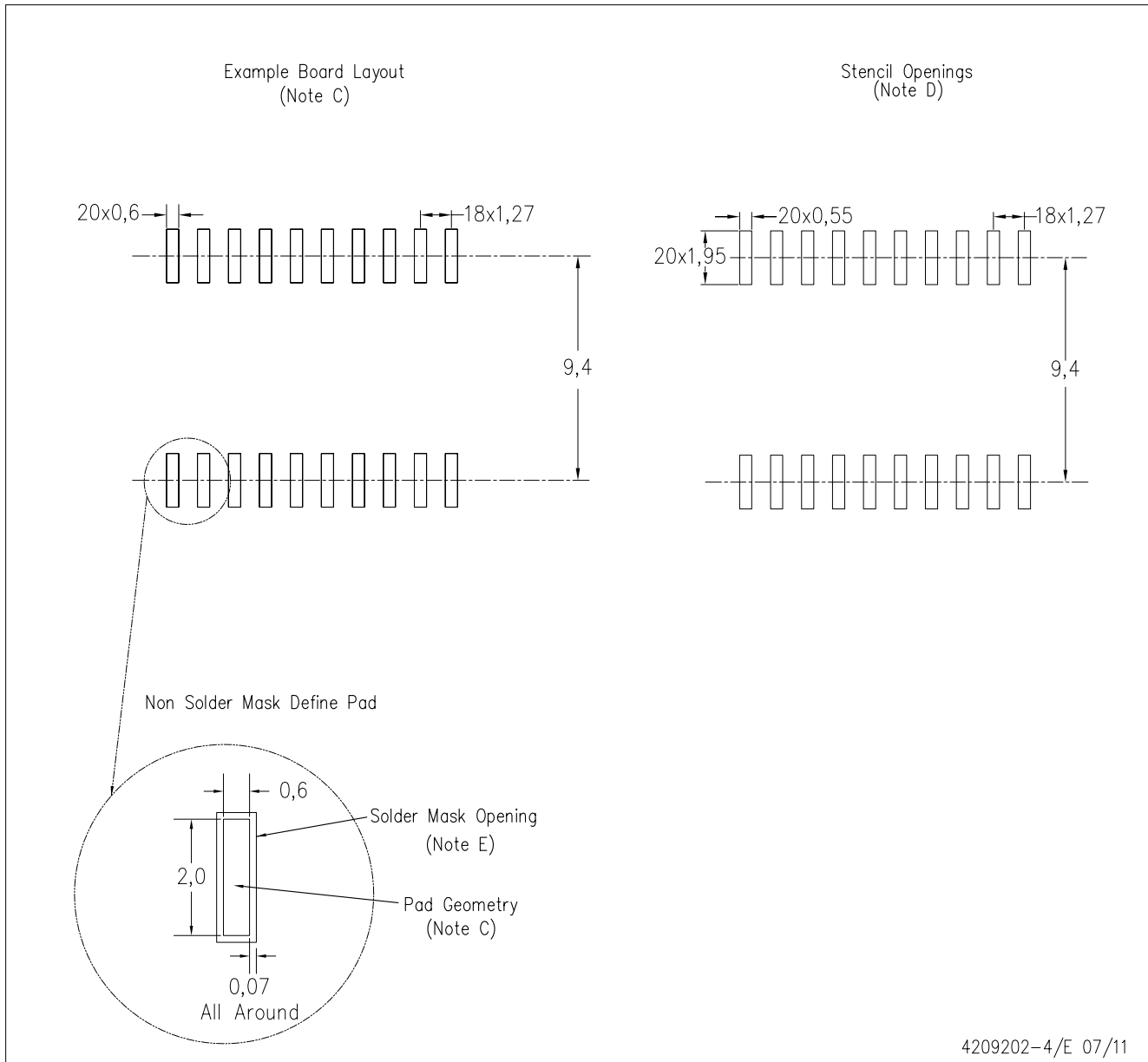
4209202−4/E 07/11

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Refer to IPC7351 for alternate board design.
        D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
            contact their board assembly site for stencil design recommendations. Refer to IPC−7525
        E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE